

ABSTRACT

Disclosed is an adhesive film in which the adhesive film contains a thermosetting resin (A), a curing agent (B),
5 a compound having flux activity (C) and a film forming resin (D), the minimum melt viscosity of the adhesive film is 0.01 to 10,000 Pa·s, and the adhesive film satisfies the following formula (1) when the exothermic peak temperature of the adhesive film is defined as (a) and the
10 5% weight loss temperature by thermogravimetry of the adhesive film is defined as (b),
$$(b)-(a) \geq 100 \text{ degrees centigrade (1)}.$$